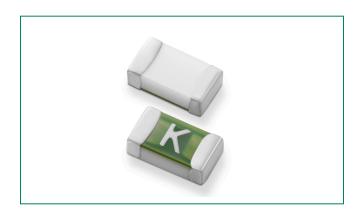
Surface Mount Fuses Ceramic Chip Fuse > 400M Series

400M Series - 0603 Low Resistance Fast Acting Fuse





Electrical Characteristics

	% of Ampere Rating	Opening Time at 25°C		
100%		4 Hours Minimum		
	200%	5 Seconds Maximum		

Additional Information







DescriptionThe 400M S

The 400M Series is an 0603 Fast Acting fuse which offers relatively low resistance best suited for application which requires such. The part is 100% Lead-free, RoHS compliant, and Halogen-free fuses designed to provide over-current protection to circuits that operate under high operating temperatures of up to 150°C.

Features

- Operating temperature from -55°C to 150°C
- 100% Lead-free, RoHS compliant, and Halogenfree
- Suitable for both leaded and lead-free soldering

Applications

• Burn-in Test

Electrical Specifications by Item

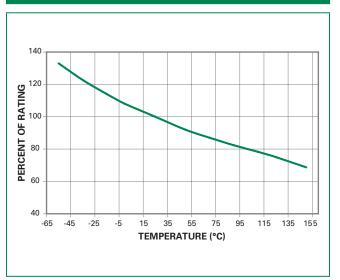
Ampere Rating (A)	Amp Code	Max. Voltage Rating (V)	Interrupting Rating	Nominal Resistance (Ohms)	Nominal Melting l²t (A²Sec.)	Nominal Voltage Drop at Rated Current (mV)	Nominal Power Dissipation at Rated Current (W)
0.5	0025	5	50A @ 5VDC	0.325	0.00169	189	0.095
1.5	0026	5	30A @ 3VDC	0.095	0.03	161	0.242

Notes

- 1. Cold resistance measured at less than 10% of rated current at 23°C.
- 2. I²t values stated for 1msec opening time.



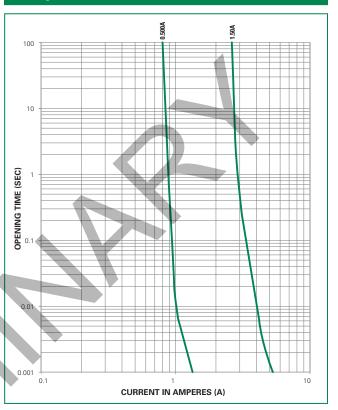
Temperature Re-rating Curve



Note:

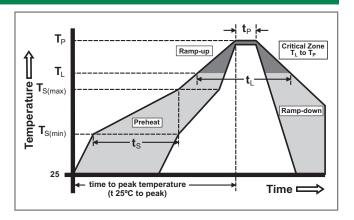
Re-rating depicted in this curve is in addition to the standard re-rating of 20% for continuous operation.

Average Time Current Curves



Soldering Parameters

Reflow Co	Reflow Condition Pb – free assembl			
	-Temperature Min (T _{s(min)})	150°C		
Pre Heat	-Temperature Max (T _{s(max)})	200°C		
	-Time (Min to Max) (t _s)	60 – 180 seconds		
Average R (T _L) to pea	amp-up Rate (Liquidus Temp k)	5°C/second max.		
T _{S(max)} to T _l	- Ramp-up Rate	5°C/second max.		
Deflow	-Temperature (T _L) (Liquidus)	217°C		
Reflow	-Temperature (t _L)	60 – 150 seconds		
Peak Temp	erature (T _P)	260+0/-5 °C		
Time with	in 5°C of actual peak ure (t _p)	20 - 40 seconds		
Ramp-dov	vn Rate	5°C/second max.		
Time 25°C	to peakTemperature (T _P)	8 minutes max.		
Do not exc	ceed	260°C		



Surface Mount Fuses Ceramic Chip Fuse > 400M Series

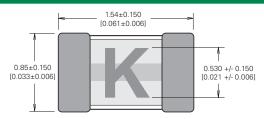
Product Characteristics

Materials	Body: Advanced Ceramic Terminations: Ag/Ni/Sn (100% Lead-free) Element Cover Coating: Lead-free Glass		
Moisture Sensitivity Level	IPC/JEDEC J-STD-020C, Level 1		
Solderability	IPC/ECA/JEDEC J-STD-002B, Condition B		
Humidity Test	MIL-STD-202, Method 103B, Conditions D		
Resistance to Solder Heat	MIL-STD-202, Method 210F, Condition B		

Moisture Resistance	MIL-STD-202, Method 106G
Thermal Shock	MIL-STD-202, Method 107,G Condition B-3
Mechanical Shock	MIL-STD-202, Method 213B, Condition A
Vibration	MIL-STD-202, Method 201A
Vibration, High Frequency	MIL-STD-202, Method 204D, Condition D
Dissolution of Metallization	IPC/ECA/JEDEC J-STD-002B, Condition D
Terminal Strength	IEC 60127-4

Dimensions

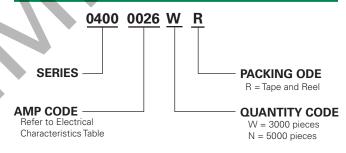
0.502±0.080 [0.020±0.003]

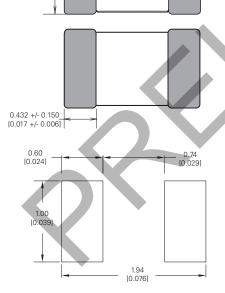


Part Marking System

Amp Code	Marking Code
0025	F
0026	K

Part Numbering System





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Packaging

Packaging Option	Form Factor	Packaging Specification	Quantity	Quantity & Packaging Code
8mm Tape and Reel	Surface Mount	EIA-481, IEC 60286, Part 3	3000	WR
8mm Tape and Reel	Surface Mount	EIA-481, IEC 60286, Part 3	5000	NR